

In re Patent Application of:  
DAIR ET AL.  
Serial No. 10/618,234  
Filed: JULY 11, 2003

IN THE CLAIMS

Claims 1-37 (Cancelled)

38. (Currently Amended) A method of assembling an opto-electronic module comprising:

forming a shielded housing with an open end, the shielded housing formed out of a sheet of conductive material to provide electromagnetic radiation shielding and protection of components, the shielded housing including one or more fingers to couple the shielded housing to ground;

assembling optical, electrical and optical-electrical components into a chassis to form a subassembly;

inserting the subassembly into the open end of the shielded housing, the shielded housing around the subassembly; and

closing the open end of the shielded housing to hold the subassembly and the shielded housing assembled together including folding a strap and a septum of the shielded housing, the strap folded across the open end to strap the subassembly into the shielded housing, the septum folded into the open end to couple to the bottom side of the shielded housing to hold the subassembly strapped into the shielded housing.

39. (Original) The method of claim 38 wherein, the shielding housing is a one-piece shielding housing to protect components and to shield electromagnetic radiation.

40. (Original) The method of claim 38 wherein, the open end is a back side and the inserting includes inserting a front end of the subassembly into the open end of the back side of the shielded housing.

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41. (Original) The method of claim 40 wherein, the closing of the open end of the back side includes folding a left side wing and a right side wing into the open end, and folding a back side flap down over the open end to couple to the left side wing and the right side wing.

42. (Original) The method of claim 38 wherein, the open end is a front side and the inserting includes inserting a rear end of the subassembly into the open end of the front side of the shielded housing.

43. (Cancelled)

44. (Previously Presented) The method of claim 38 wherein, the forming of the shielded housing includes stamping a pattern of the shielded housing into the sheet of conductive material, the pattern including the one or more fingers near an edge of the flat sheet, folding the sheet of conductive material along a plurality of fold lines into a multi-sided rectangularly shaped container but for the open end, and bending the one or more fingers into shape.

Claims 45-63 (Cancelled)

64. (Original) A method to assemble an EMI shielding module comprising:  
forming a plurality of substantially equidistant spring fingers along an edge of a flat sheet;  
forming a strap at the edge of the flat sheet and a septum on the end of the strap;  
forming a pair of bottom flaps in the flat sheet;  
folding the flat sheet along axes to form a container substantially in the shape of rectangular box, the rectangular box having a first end and a second end,

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the first end having the plurality of fingers along each of a plurality of edges and an opening for cable connectors, the second end having a backside flap;

folding the strap across the opening for cable connectors; and

coupling the septum to inner surfaces of the bottom flaps to hold the strap across the opening.

65. (Original) The method of claim 64 wherein, the EMI shielding module is a one-piece shielded housing to protect components and to shield electromagnetic radiation.

66. (Original) The method of claim 64 wherein, the EMI shielding module encloses a module chassis frame, the module chassis frame being a central structural support to which one or more optical, electrical and optical-electrical components used in transmission and reception of optical signals are attached.

Claims 67-76 (Cancelled)

77. (Original) A method to assemble an optical transmitter and/or receiver, the method comprising:  
forming a plurality of fingers, a strap, and a septum along a first edge of a conductive sheet;  
placing the conductive sheet on a module chassis frame, the module chassis frame having a plurality of components used in transmitting and/or receiving optical signals;  
folding the conductive sheet around the module chassis frame such that the conductive sheet substantially encloses the module chassis frame but for a frontal opening adjacent to the first edge; and

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bending the strap and the septum around a front end  
of the module chassis frame to hold the folded conductive  
sheet and the module chassis frame together.

78. (Cancelled)

79. (Original) The method of claim 77 wherein, the fingers to electrically ground the folded conductive sheet to a ground of a host system.

80. (Original) The method of claim 77 wherein, the conductive sheet is one of metal, conductive plastic, and plated plastic.

81. (Original) The method of claim 77 further comprising: bending the plurality of fingers outward from the frontal opening.

82. (Original) The method of claim 77 further comprising: lifting the plurality of fingers up from an outer surface of the conductive sheet.

Claims 83-133 (Cancelled)